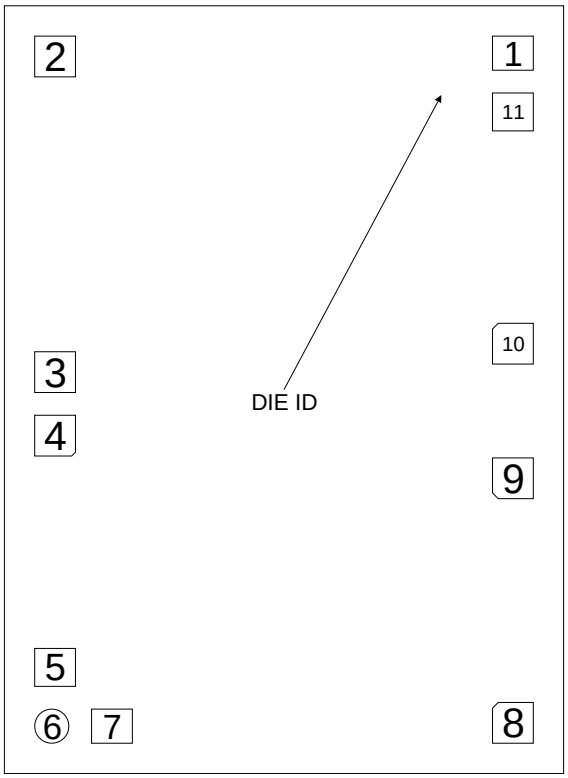
LM119 MDR MCD2910A
HIGH SPEED DUAL COMPARATOR

AUG 22, 2008

DIE LAYOUT (C-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM119C	Bond Pad Opening Size (min)	109.22µm x 91.44µm
Die Step	C	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	VOM ONLY
Wafer Diameter	150mm	Back Side Metal	BAREBACK
Die Size (Drawn)	1498.6µm x 2057.4µm 59.0mils x 81.0mils	Back Side Connection	V -
Thickness	330µm Nominal		
Min Pitch	157µm		
Note: All values are rounded to the nearest micron.			
Special Assembly Requirements:			

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Die Bond Pad Coordinate Locations(C-Step)
(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X		Y
Output 1	1	613	901	109	x	91
Gnd 1	2	-613	892	109	x	109
+Input 1	3	-613	46	109	x	109
-Input 1	4	-613	-123	109	x	109
V-	5	-613	-744	109	x	101
NC	6	-622	-901	91	x	91
Output 2	7	-461	-901	109	x	91
Gnd 2	8	613	-892	109	x	109
+Input 2	9	613	-237	109	x	109
-Input 2	10	613	123	109	x	109
V+	11	613	744	109	x	101

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Notes

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